# 2SB647, 2SB647A

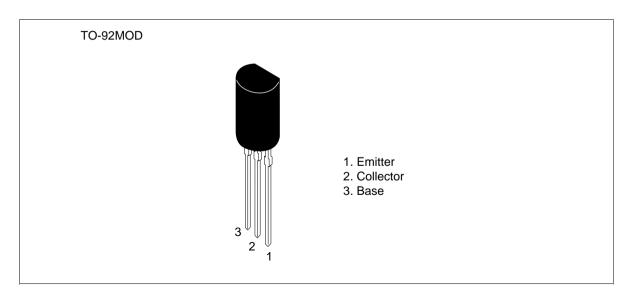
Silicon PNP Epitaxial

# **HITACHI**

### **Application**

- Low frequency power amplifier
- Complementary pair with 2SD667/A

### Outline



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## 2SB647, 2SB647A

## **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

Item	Symbol	2SB647	2SB647A	Unit
Collector to base voltage	$V_{\text{CBO}}$	-120	-120	V
Collector to emitter voltage	$V_{\text{CEO}}$	-80	-100	V
Emitter to base voltage	V <sub>EBO</sub>	<b>-</b> 5	<b>-</b> 5	V
Collector current	I <sub>c</sub>	-1	<b>-1</b>	A
Collector peak current	i <sub>C(peak)</sub>	-2	-2	A
Collector power dissipation	P <sub>c</sub>	0.9	0.9	W
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

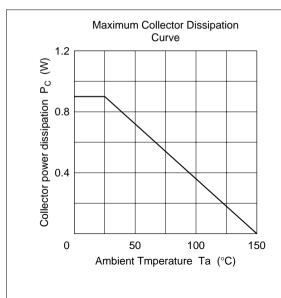
### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

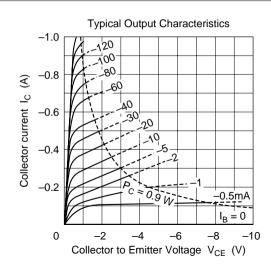
		2SB6	47		2SB6	47A			
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-120	_	_	-120	_	_	V	$I_{\rm C} = -10 \ \mu A, \ I_{\rm E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-80	_	_	-100	_	_	V	$I_{\rm C} = -1 \text{ mA}, R_{\rm BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	<b>-</b> 5	_	_	<b>-</b> 5	_	_	V	$I_{E} = -10  \mu A, I_{C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	-10	_	_	-10	μΑ	$V_{CB} = -100 \text{ V}, I_{E} = 0$
DC current transfer ratio	h <sub>FE1</sub> *1	60	_	320	60	_	200		$V_{CE} = -5 \text{ V},$ $I_{C} = -150 \text{ mA}^{*2}$
_	h <sub>FE2</sub>	30	_	_	30	_	_		$V_{CE} = -5 \text{ V},$ $I_{C} = -500 \text{ mA}^{*2}$
Collector to emitter saturation voltage	$\boldsymbol{V}_{\text{CE(sat)}}$	_	_	-1	_	_	<b>–</b> 1	V	$I_{\rm C} = -500 \text{ mA},$ $I_{\rm B} = -50 \text{ mA}^{*2}$
Base to emitter voltage	$V_{\text{BE}}$	_	_	-1.5	_	_	-1.5	V	$V_{CE} = -5 \text{ V},$ $I_{C} = -150 \text{ mA}^{*2}$
Gain bandwidth product	$f_{T}$		140			140		MHz	$V_{CE} = -5 \text{ V}, I_{C} = -150 \text{ mA}$
Collector output capacitance	Cob	_	20	_	_	20	_	pF	$V_{CB} = -10 \text{ V}, I_{E} = 0$ f = 1 MHz

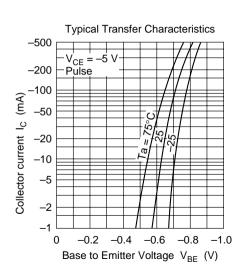
Notes: 1. The 2SB647 and 2SB647A are grouped by h<sub>FE1</sub> as follows.

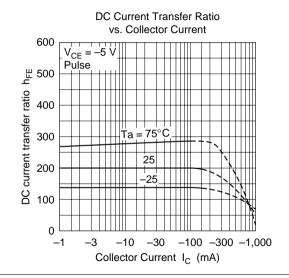
2. Pulse test

	В	С	D
2SB647	60 to 120	100 to 200	160 to 320
2SB647A	60 to 120	100 to 200	_



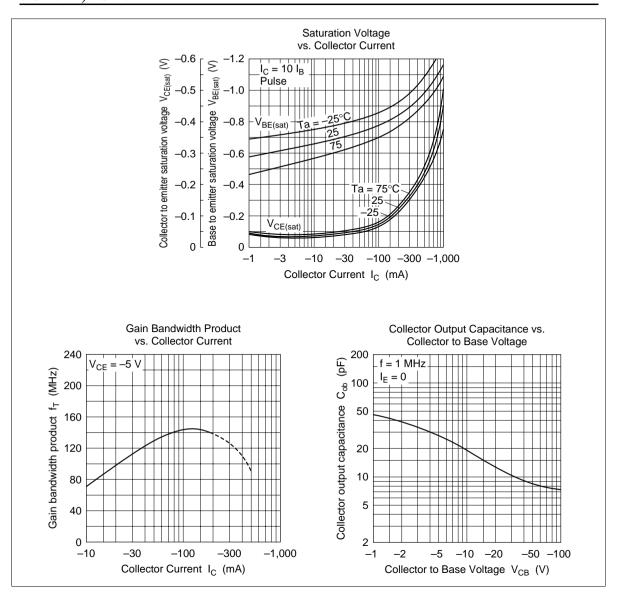






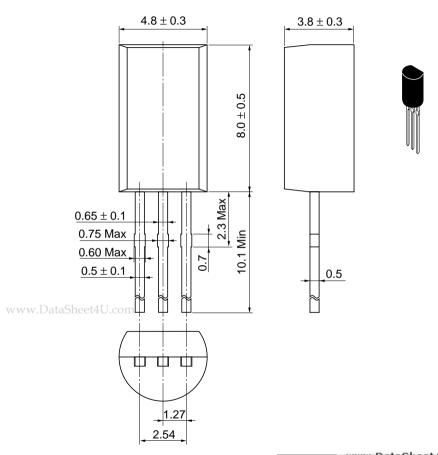
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## 2SB647, 2SB647A



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Unit: mm



Hitachi Code WWW.DataSheet 40.com				
JEDEC				
EIAJ	Conforms			
Weight (reference value)	0.35 g			

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#### Hitachi, Ltd.

Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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#### For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 4 Tel: <49> (89) 9 9180-0

Hitachi Europe GmbH Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany

Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead

Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd. Taipei Branch Office 3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218

Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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